LCTPC/LPWP-11th phonemeeting

- Date 11 October 2006
- Time
 - 7:00 west coast
 - 10:00 east coast
 - 16:00 central Europe
 - 23:00 Japan
- To join,

Phone +494089981390 code 52872#

Agenda for 11th WP phonemeeting

(in future the meetings will be managed via http://ilcagenda.cern.ch/)

AGENDA

-1.News

a.http://ilcagenda.cern.ch/

b.Formation of the LCTPC/LP Collaboration

c.WWS-R&D-panel tracking review at Beijing

-2.WP meeting

WP meeting, other contributions (whoever is ready)

-3. Future meetings

-Eudetmeeting at MPI 18-20 October

-Valencia European WS 6-10 November

-Beijing Asian WS February 3-7 February

-1a.http://ilcagenda.cern.ch/

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-1b.Formation of the LCTPC/LP collaboration

- -The proposed structure is shown on the next foil #5.
- -The Collaboration-Board (CB) of group representatives is complete for the groups on foil # 6
- -Names of both CB and TB are shown on foils #7,8.
- -A proposal by the interim-SP for the next steps was sent to the CB and TB, a first meeting held on 20.9.2006 and a second collaboration phonemeeting held on 04.10.2006
- -It was decided at the first collaboration phonemmeeting that each region should independently select a Regional Coordinator, (RC) via vote by that region's CB members, to replace the interim SPs, and that the 3 Regional Coordinators would choose a chairperson who is the sole Spokesperson. The status is:

--America: RC is Dean Karlen

- --Asia: the search committee, Keisuke Fujii and Angelina Bacala, establised the RC candidates who were be voted on by the Asia CB members. Result: RC is Takeshi Matsuda
- --Europe: the search committee, Vincent Lepeltier and Klaus Desch, will find the RC candidates who will be voted on by the European CB members.

Formation of the LCTPC/LP collaboration

The revised structure is to have:

1)Three coordinators, one chosen by each region. These regional coordinators (RC) will work with the following two boards:

2)The collaboration board (CB), consisting of one representative from each group or set of groups (the group leader, principle investigator or other chosen member). Each CB member looks after the resources for its group(s) (money and people).

3)The technical board (TB), consisting of the existing workpackage (WP) conveners. The TB will ensure the technical integrity of their WP and compatibility with other WPs while maintaining close contact with the collaboration.

The groups and names of CB and TB members are listed in the next 3 slides.

LCTPC/LP Groups (19Sept06)

Americas Carleton Montreal Victoria Cornell Indiana LBNL Purdue (observer) Asia Tsinghua CDC: Hiroshima KEK Kinki U Saga Kogakuin Tokyo UA&T U Tokyo U Tsukuba Minadano SU-IIT

Europe LAL Orsay IPN Orsay CEA Saclay Aachen Bonn DESY U Hamburg Freiburg MPI-Munich TU Munich (observer) Rostock Siegen NIKHEF Novosibirsk Lund CERN

Other groups

MIT

MIT (LCRD) Temple/Wayne State (UCLC) Yale Karlsruhe UMM Krakow Bucharest 11/10/2006

The CB members are:

--Americas-Carleton: Madhu Dixit Montreal: Jean-Pierre Martin Victoria: Dean Karlen Cornell: Dan Peterson Indiana: Rick Van Kooten LBNL: Mike Ronan

--Asia-Tsinghua: Yuanning Gao For the following CDC groups: Akira Sugiyama Hiroshima KEK Kinki Saga Kogakuin Tokyo U A&T U Tokyo Tsukuba

Mindanao

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--Europe-LAL Orsay/IPN Orsay: Vincent Lepeltier CEA Sacly: Paul Colas Aachen: Stefan Roth Bonn: Klaus Desch Desy/UHamburg: Ties Behnke Eudet: Joachim Mnich Freiburg: Andreas Bamberger **MPI-Munich:** Ariane Frey Rostock: Henning Schroeder (deputy: Alexander Kaukher) Siegen: Ivor Fleck Nikhef: Jan Timmermans Novosibirsk: Alexei Buzulutskov St.Peterburg: Anatoliy Krivchitch Lund: Leif Jonsson CERN: Michael Hauschild (deputy: Lucie Linsen)

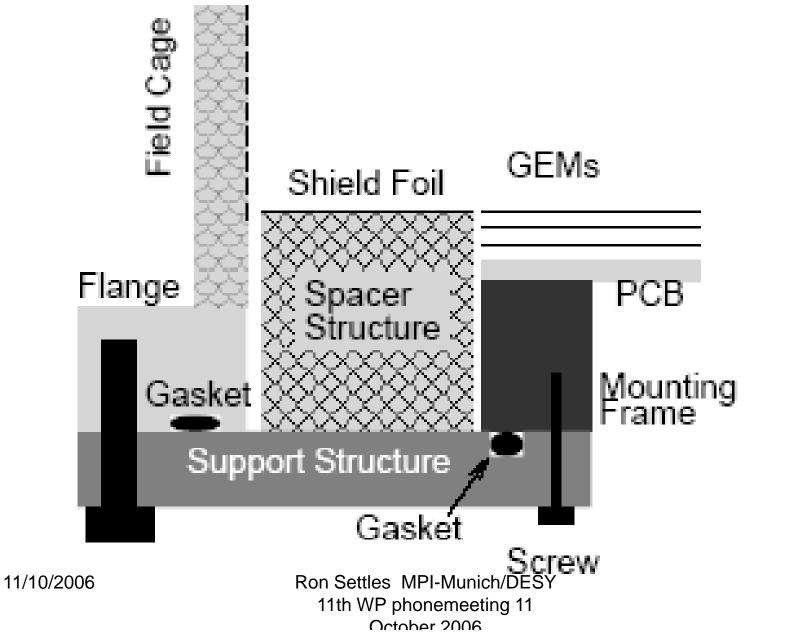
--Groups with Observer status-TU Munich: Bernhard Ketzer Purdue: Ian Shipsey

--Since replies are still missing from: MIT Yale Karlsruhe Krakow Bucharest, these groups are included as "observer groups" at the moment The TB members are:

1) Workpackage Mechanics Ron Settles a) LP design (incl. endplate structure) Dan Peterson b) Fieldcage, laser Ties Behnke c) GEM panels for endplate Akira Sugiyama d) Micromegas panels for endplate Paul Colas Jan Timmermans e) Pixel panels for endplate f) Resistive foil for endplate Madhu Dixit 2) Workpackage Electronics Leif Jonsson a)"Standard" RO/DAQ sytem for LP Leif Jonsson+Postdoc b) CMOS RO electronics Harry van der Graaf c) Electronics for LCTPC Luciano Musa 3) Workpackage Software Peter Wienemann a) LP SW, simul./reconstr.framework Peter Wienemann Stefan Roth b) TPC simulation, backgrounds c) Full detector simulation Keisuke Fujii 4) Workpackage Calibration Dean Karlen Lucie Linssen a) Field map b) Alignment Takeshi Matsuda c) Distortion correction Dean Karlen d) Radiation hardness of materials Anatoliy Krivchitch e) LP Gas/HV Eudet Postdoc Ron Settles MPI-Munich/DESY 11/10/2006 11th WP phonemeeting 11 October 2006

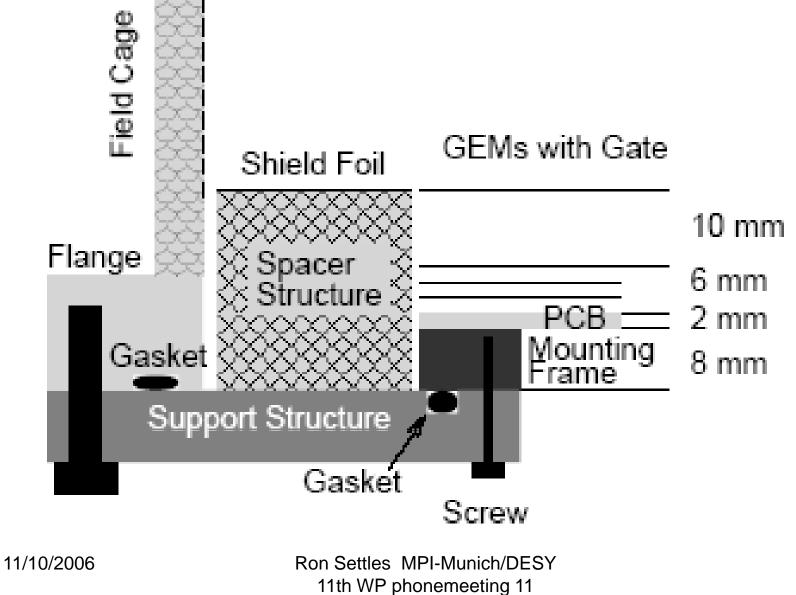
AGENDA -1c.Tracking review at Beijing:some info.....

-2. WP meeting (Martin GemLP)



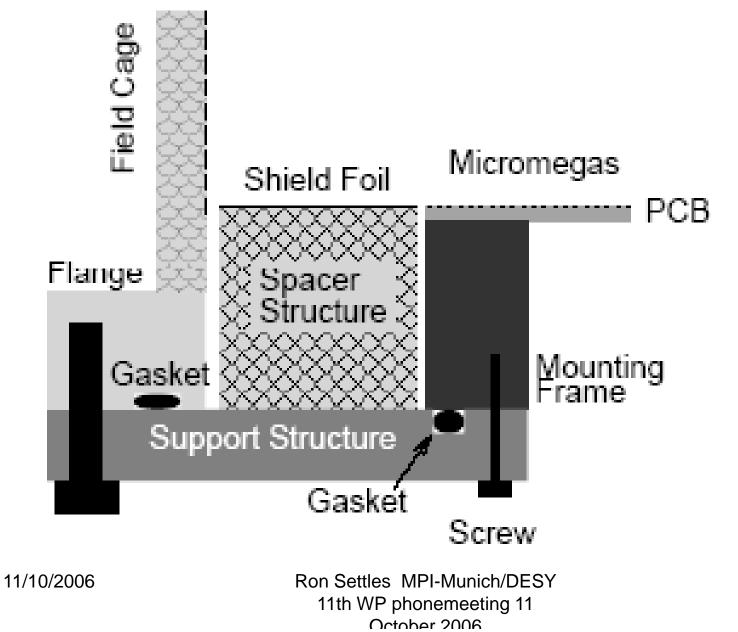
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-2. WP meeting (Martin-GemLP w/gate)

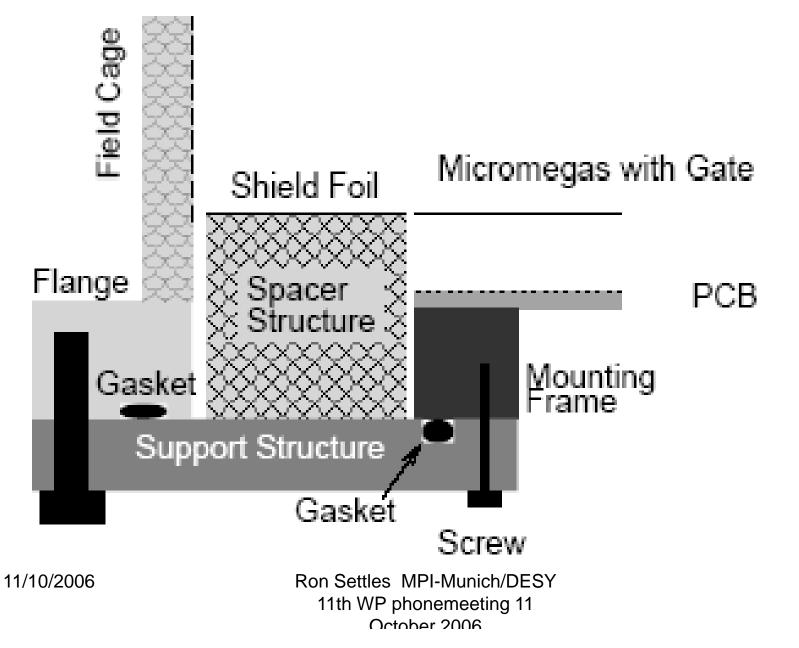


October 2006

-2. WP meeting (Martin-MicromegasLP)

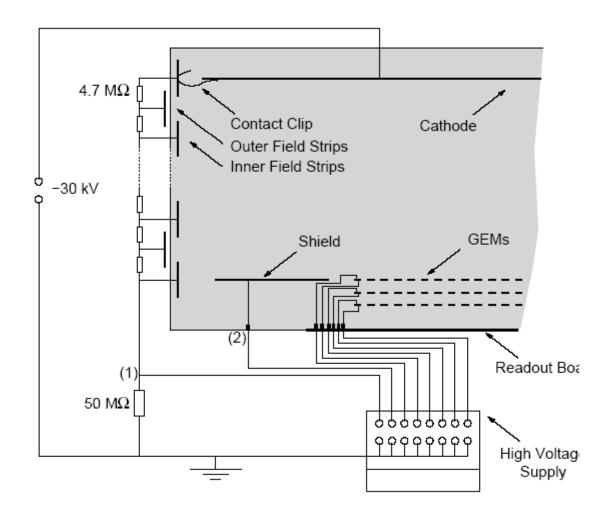


-2. WP meeting (Martin-MicromegasLP w/gate)

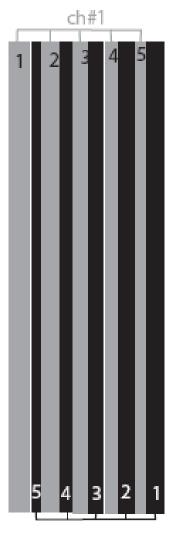


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-2. WP meeting (Martin-LPelectro)



-2. WP meeting (Yannis idea)



ch#2

-2. WP meeting (Leif & Dan on connectors, Peter on the field cage -> see the meeting summary).

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-3.Future meetings There are (in addition to bi-weekly phonemeetings):

-Eudet annual meeting MPI-Munich (18-20 October 2006) with website:

<u>http://www.eudet.org/AnnualMeeting2006/AnnualMeeting2006.html</u> The LCTPC CB/TB meeting will be at 10:30 on Wednesday 18 Oct., before the start of the Eudet one at 14:00.

-European LC workshop Valencia (6-10 November 2006), see http://ific.uv.es/~ilc/ECFA-GDE2006/

-Asian LC workshop Beijing (4-7 February 2007) Website: <u>http://bilcw07.ihep.ac.cn/</u>

AGENDA -4.AOB

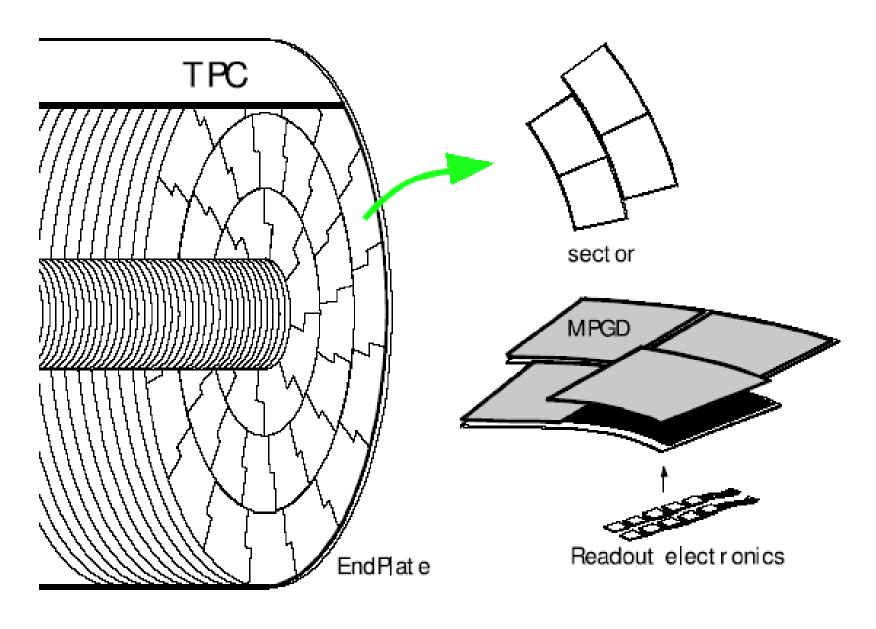
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Back up slides, for reference

11/10/2006

Akira Sugiyama – GLD DOD

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RS study - LDC DOD - together with

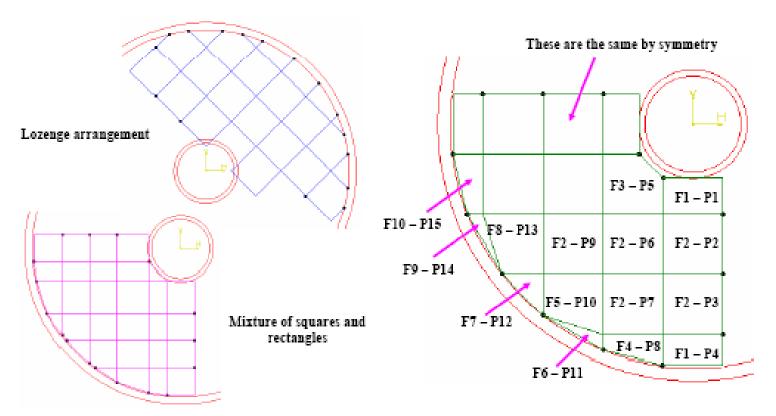
Joel Pouthas Philippe Rosier (IPN Orsay)

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Arrangements of detectors on the active area of the end cap (1/2) Squares, rectangles, lozenge of 300/350 mm or 400 mm size



Annotations: F is the type number of frames / P is for the PADS board



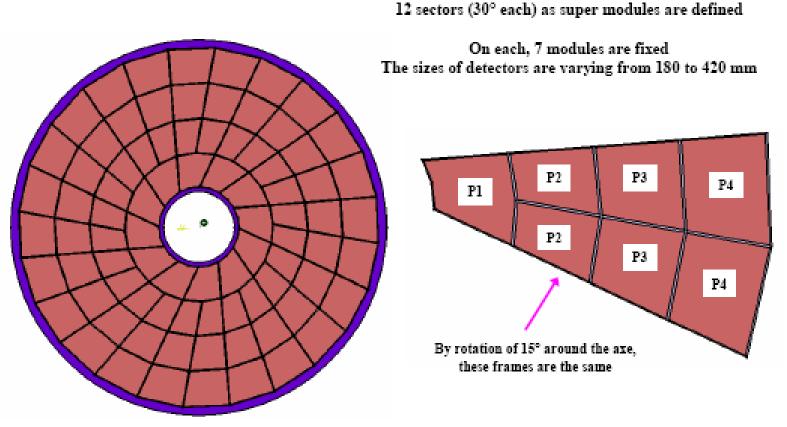
These arrangements need too much different sorts of frames and PADS boards, even if the right drawing is the simplest

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Arrangements of detectors on the active area of the end cap (2/2) Trapezoidal shapes assembled in iris shape



Annotations: Px is the type number of PADS boards or frames

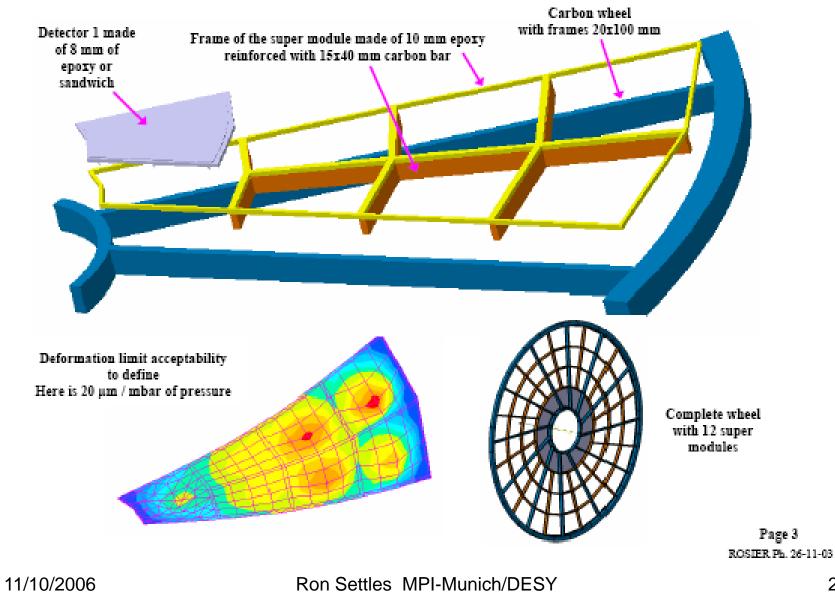


These arrangement seems to be the best as only 4 different PADS are necessary

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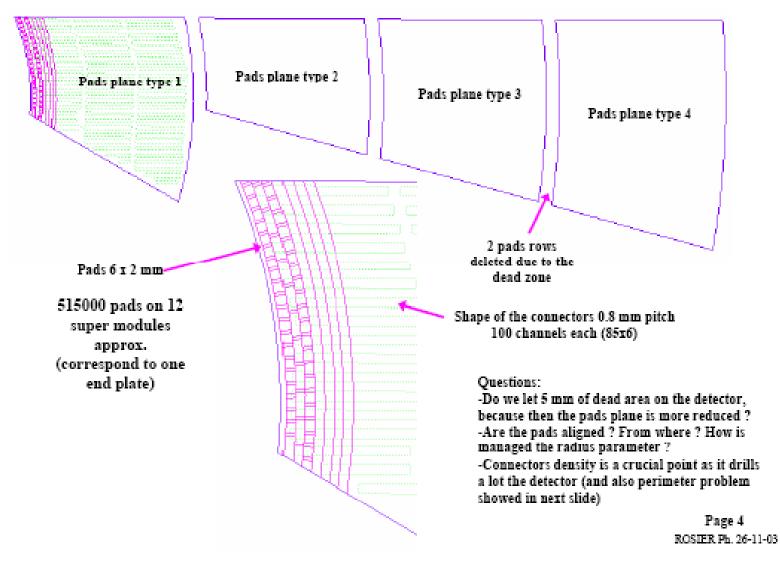
Principle for a Super Module equipped with detector 1





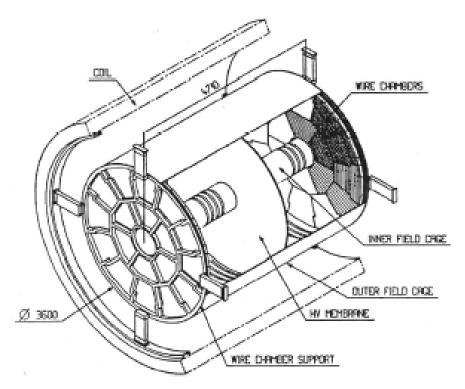
Principle for the 4 types of Pads plane





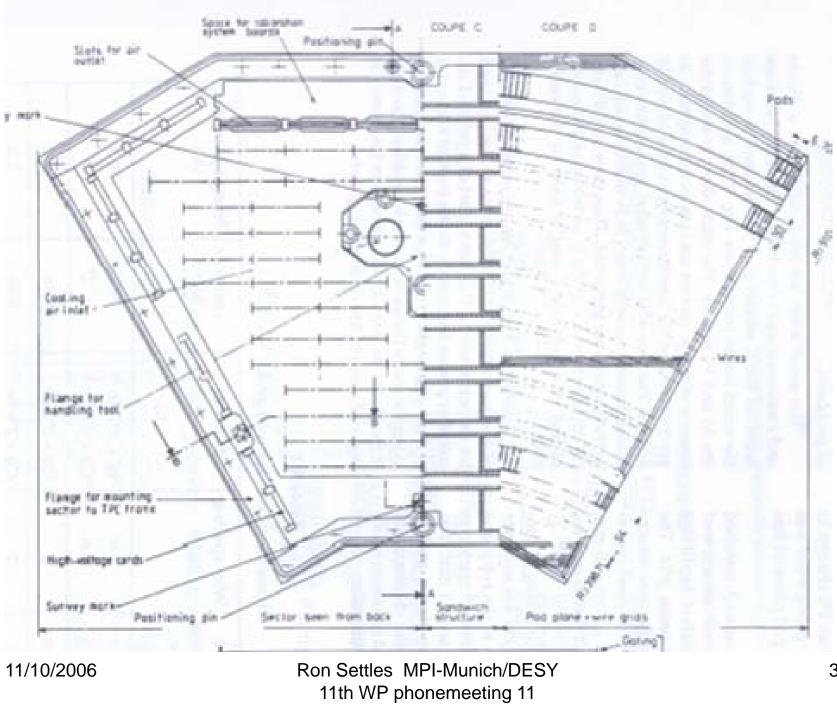
Aleph Endplate

TPC

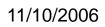


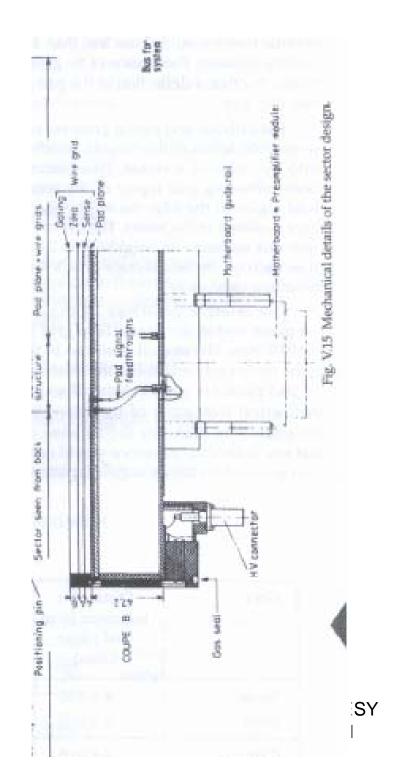
rφ from pad position
z from drift time (pads + wires)
dE/dx from wires and pads

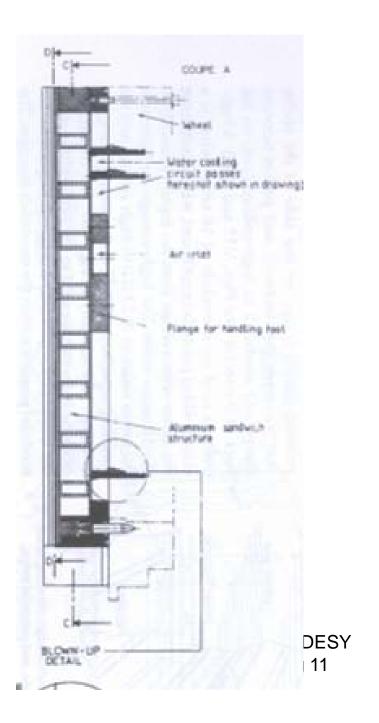
- Length = 4.7 m
- Outer radius = 1.8 m
- Total weight = 3.6 t
- Drift length $2 \times 2.2m$
- Up to 21 space points / track
- 18 wire chambers / endplate
- 47340 channels in total
- B = 15 kG
- HV (Membrane) = -27.5 kV
- Gas
 - Volume $43 m^3$
 - Argon/Methan (91:9) at atmospheric pressure
- Angular coverage
 - 2π in φ
 - 21 pad rows hit for $\cos \Theta \le 0.8$
 - At least 3 pad rows for $\cos \Theta \le 0.97$



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Some features

- Zigzag structure prevented loss of tracks > θ~22°
- Sectors mounted from inside using a "handling tool" to minimize the dead space between sectors. This straight-forward operation which was performed at least 30 times during the lifetime of Aleph.
- Alu sandwich structure stiff, lightweight to
 - contain 7mb overpressure
 - provide forced-air thermal insulation between electronics and TPC volume
- Water cooling of 1kW electronics/side in addition
 - 22K channels per side
- Combination water/air cooling blocked all heat to TPC
- Overall thickness ~ 25%Xo (average) w/o cables
- Bending of endplate
 - 20 micrometers due to 7mb overpressure
 - 5 micrometers due to wire tension

R&D Planning

- 1) Demonstration phase
 - Continue work with small prototypes on mapping out parameter space, understanding resolution, etc, to prove feasibility of an MPGD TPC. For CMOS/Si-based ideas this will include a basic proof-of-principle.
- 2) Consolidation phase
 - Build and operate the LP, large prototype, ($\emptyset \ge 75$ cm, drift ≥ 100 cm), with EUDET infrastructure as pedestal, to test manufacturing techniques for MPGD endplates, fieldcage and electronics. Design is starting---building and testing will take another ~ 3 years.
- 3) Design phase
 - After phase 2, the decision as to which endplate technology to use for the LC TPC would be taken and final design started.